



Material Content Data Sheet



Sales Product Name		IPU80R1K4CE		Issued		19. July 2018			
MA#		MA001128114							
Package		PG-TO251-3-341		Weight*		382.74 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.894	1.02	1.02	10173	10173	
leadframe	non noble metal	iron	7439-89-6	0.229	0.06		599		
	inorganic material	phosphorus	7723-14-0	0.069	0.02		180		
	non noble metal	copper	7440-50-8	228.946	59.81	59.89	598184	598963	
wire	non noble metal	aluminium	7429-90-5	0.428	0.11	0.11	1117	1117	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.713	0.45		4476		
	plastics	brominated resin	-	1.836	0.48		4796		
	organic material	carbon black	1333-86-4	1.958	0.51		5116		
	plastics	epoxy resin	-	16.520	4.32		43163		
	inorganic material	silicondioxide	60676-86-0	100.344	26.22	31.98	262175	319726	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9772	9772	
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1330	1330	
solder	noble metal	silver	7440-22-4	0.084	0.02		219		
	non noble metal	tin	7440-31-5	0.067	0.02		175		
	non noble metal	lead	7439-92-1	3.198	0.84	0.88	8354	8748	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.00		50		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.01	5.01	50106	50171	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com